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EOL of 50nm LPDDR2 512Mb (U67M) and 1Gb (U67M DDP)

PCN: 31719

Published: 2015-10-30

Type:	Die Shrink/Technology Transition, End of Life
Description:	Micron's 50nm 512Mb LPDDR2 (U67M) and 1Gb LPDDR2 (U67M DDP) is being replaced by 25nm process technology 512Mb LPDDR2 (U97M) and 1Gb LPDDR2 (U98M). With this change, solderball composition will change for some parts listed from SAC305 to SAC302. Please refer to the datasheet for details.
Reason:	Manufacturing Efficiency
Product Affected:	50nm 512Mb LPDDR2 (U67M) and 1Gb LPDDR2 (U67M DDP)

Affected Micron Part Number	Recommended Replacement	Customer Part Number
<u>Wafer</u>		
MT42L16M32D1AC-25 IT:A	EDB5432BEBH-1DIT-F-R	
MT42L16M32D1U67MWC2	Contact Factory	
MT42L32M16D1FE-25 IT:A	Contact Factory	
MT42L32M16D1U67MWC1	Contact Factory	
MT42L32M16D1U67MWC2	Contact Factory	

*Materials that have been ordered are in **bold**.

Method of Identification:	Marketing Part Number
Micron Sites Affected:	All Sites
Sample Available:	2015-09-15
Qual Data Available:	2015-10-01
Last Purchase Date*:	2016-04-30
Last Shipment Date:	2016-10-30

**Orders placed prior to the last purchase date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged.*

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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Thank you

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